

SWAN

Cross section Test report review

SH Son

Model Name: BFX-UA300

Document Version: ALT_STB_MP_CSMTINS_001

Issued Date: 2022.08.23



ALT

All Life Technology Co., Ltd

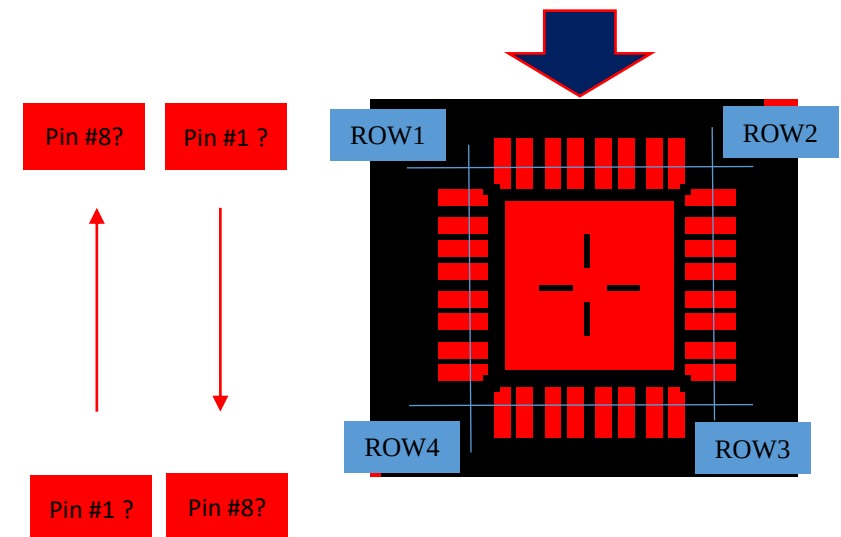
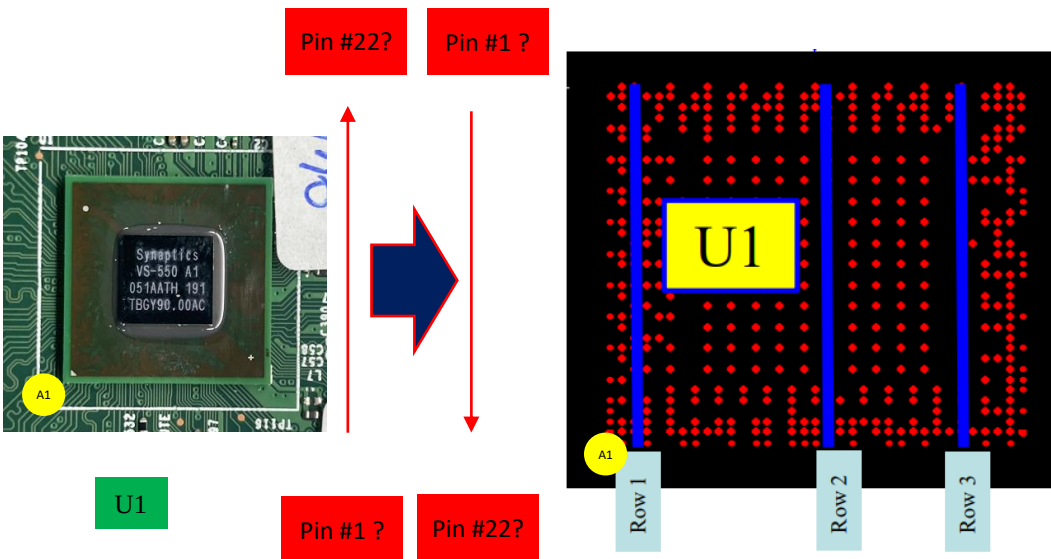


Confidential

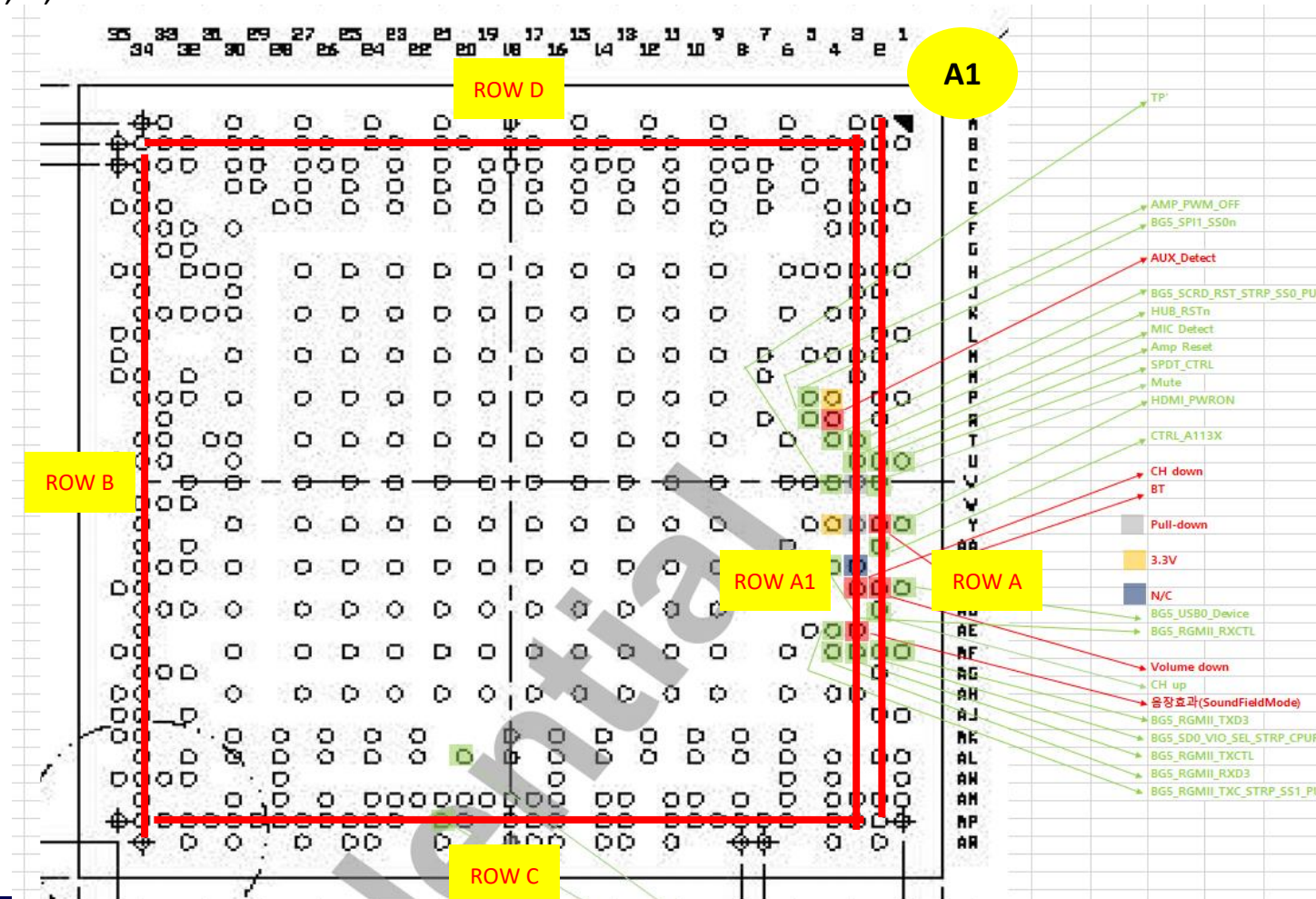
Document History

Version	Editor	Date	Updates
001	SH Son (Seunghwan Son)	2022.08.12	initial version
002	SH Son (Seunghwan Son)	2022.08.23	Feedback of SWAN (K18X001.00) Cross section Test Overview (2022.08.19)

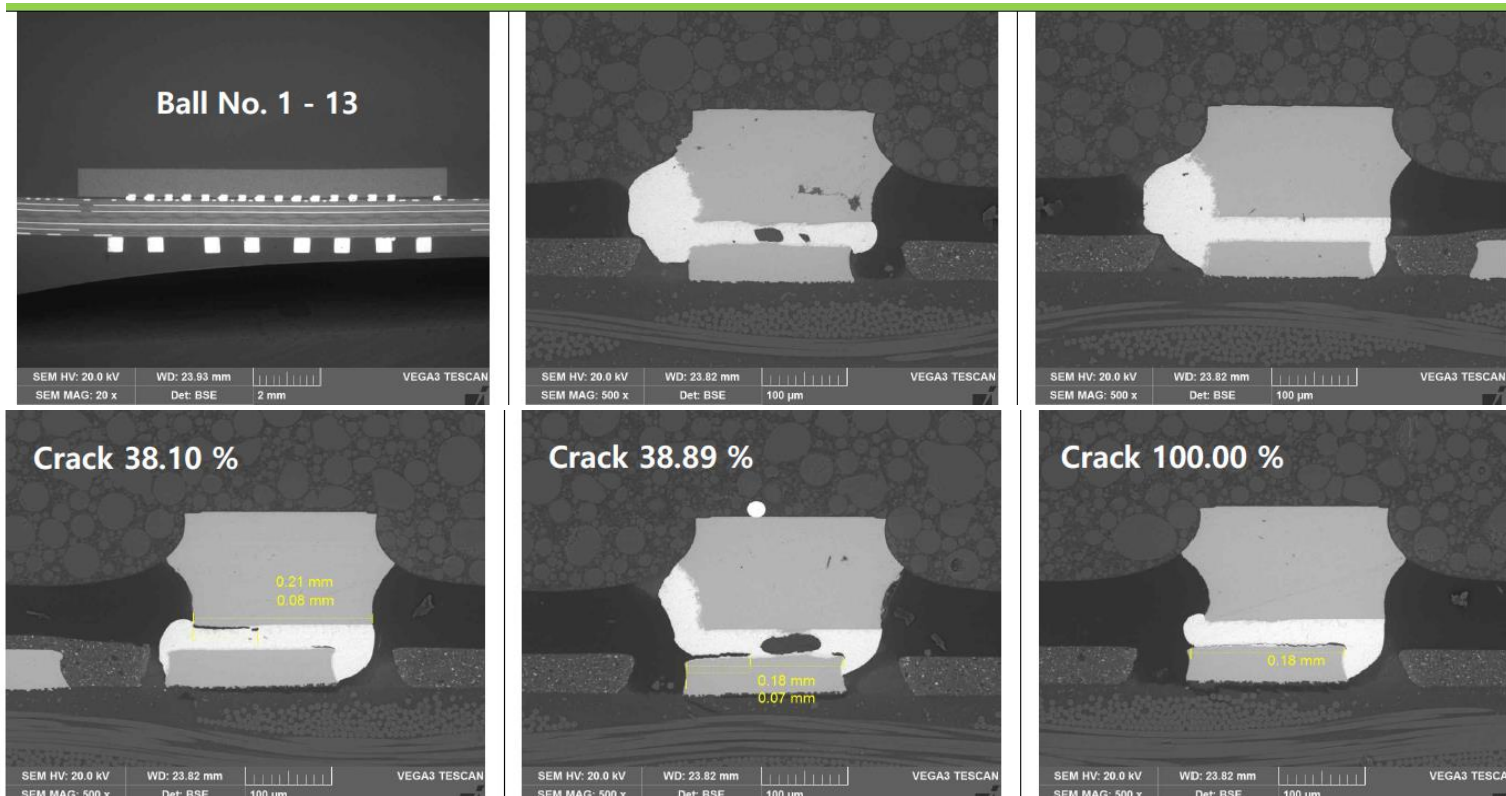
- Update the section direction
 - Where is point start #1 ?
- Please explain why chose the section Row 1, 2, 3?



- Please check possible to add a section line
 - Row B, C, D
 - If proceed Next section test, please analysis below in order
 - Row A, A1, B, C, D



- Please polish more with finer sandpaper.
 - It is difficult to distinguish between the IMC layer and the solder layer because the image is not clear.
 - After polish, update the image : red marked pin
 - Add the add 500x image
 - Add the SAM image
 - i.g. SAM image



- Red point
 - Add the add 500x image
 - Add the SAM image

A. Location U1 (BGA)-Magnify*200x:

❖ Row-1

1#	2#	3#	4#	5#	6#	7#	8#	9#	10#	11#
12#	13#	14#	15#	16#	17#	18#	19#	20#	21#	22#

❖ Row-3

1#	2#	3#	4#	5#	6#	7#	8#	9#	10#	11#	12#
13#	14#	15#	16#	17#	18#	19#	20#	21#	22#	23#	NA

A. Location U1 (BGA):

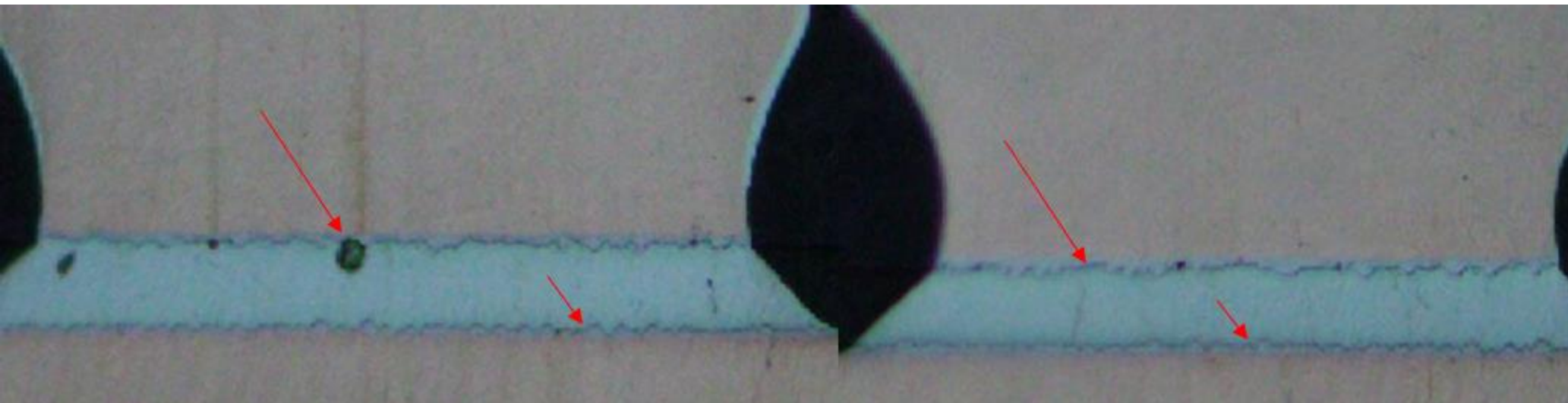
❖ Row-2

1#	2#	3#	4#	5#	6#	7#	8#
9#	10#	11#	12#	13#	14#	15#	NA

- B. Location U1313 (QFN) Row-4 : 6#, 7#
 - In my opinion, it is judged as a IMC layer crack
 - Prove it's not a solder crack

Row-4 6#

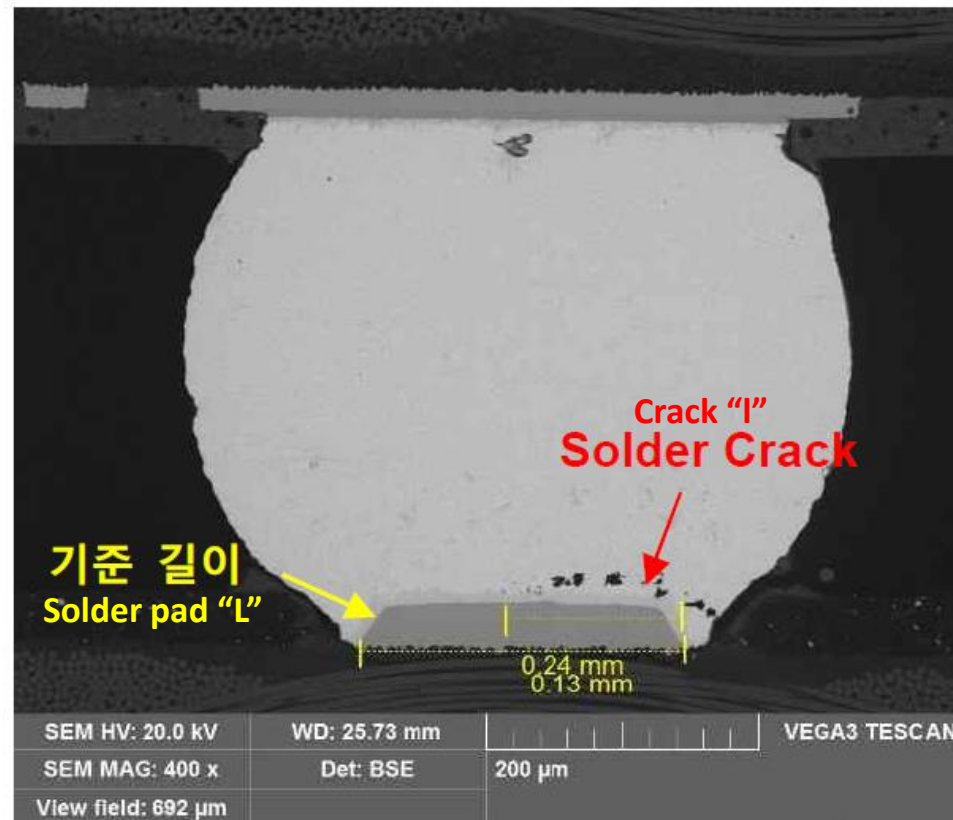
Row-4 7#



Confidential

- Define the Solder crack

- Solder Crack (%) : Crack "l" / solder Pad "L" X 100
- ※ criteria : Solder Crack < 25 %
 - $0.13/0.24 \times 100 = 54.16\%$



Confidential

Thank you.

ALT
All Life Technology Co., Ltd

Confidential